WLTE7002E55

Wi-Fi 7 (802.11be) Dual-Band Wireless Module

Hardware User Guide

Wi-Fi 7 / 802.11be 5GHz (5-L) + 5GHz (5-H)	**QCN6224 / QCN6274 / QCN9274-I** Qualcomm Waikiki Series	**M.2 E Key Interface** PCIe 3.0 Compatible	**2×2 MU-MIMO** Up to 4324 Mbps

Updated: 20260826

Contents

1. Introduction **3**
2. Package Contents **4**
3. Hardware Overview **5**
3.1 Module Layout 5
3.2 Connector Descriptions 6
3.3 Hardware Pinouts 7
4. Radio Module Specifications **8**
4.1 Wi-Fi Capability 8
4.2 Notes & Recommendations 8
5. Mechanical Specifications **9**
5.1 Module Dimensions 9
5.2 Environmental Ratings 9
5.3 Mounting & Installation Notes 9
6. Power Specifications **10**
6.1 Power Requirements 10
6.2 Power Delivery Protection 10
6.3 Notes & Recommendations 10
7. Installation & Integration **11**
7.1 Pre-Installation Checklist 11
7.2 Module Installation 11
7.3 Power Connection 11
7.4 Antenna Connection 11
8. Troubleshooting **12**
9. Safety Precautions **13**
10. Technical Support **14**
11. Full Specifications **15**
12. Regulatory Information **16**

1. Introduction

Thank you for choosing the Compex WLTE7002E55. This document provides complete hardware integration guidance for engineers and system developers deploying the WLTE7002E55 Wi-Fi 7 wireless module in embedded, industrial, and networking platforms.

The WLTE7002E55 is a dual-band concurrent Wi-Fi 7 (802.11be) wireless module based on the Qualcomm QCN6224/6274 'Waikiki' series chipset (commercial grade) or the QCN9274-I 'Waikiki' series chipset (industrial grade). Built on the WK01.4 reference design, the module delivers 2×2 MU-MIMO operation across two concurrent 5GHz sub-bands, 5GHz-Low (5-L) and 5GHz-High (5-H) simultaneously through a standard M.2 E Key (PCIe 3.0) host interface.

Key Highlights

- Qualcomm QCN6224/6274 'Waikiki' series chipset for commercial-grade deployments.
- Qualcomm QCN9274-I 'Waikiki' series chipset for industrial-grade deployments.
- 5GHz (5-L), 2×2 MU-MIMO, up to 4324 Mbps physical data rate.
- 5GHz (5-H), 2×2 MU-MIMO, up to 4324 Mbps physical data rate.
- Dual-Band Concurrent 5GHz (5-L) + 5GHz (5-H) Wi-Fi 7 (802.11be) operation.
- M.2 E Key interface with PCIe 3.0 host connectivity.
- Based on the WK01.4 reference design.
- Supports up to 4096-QAM (4K-QAM) modulation.
- Operating temperature: -20°C to 70°C with standard heatsink (customized heatsink solutions available for extended industrial-grade requirements).
- FCC, CE, IC Certified; REACH and RoHS compliant for global deployment.

2. Package Contents

Verify the following items are included in the package before proceeding with installation:

Checklist

- 1 × WLTE7002E55 Wi-Fi 7 wireless module

> ⚠ **Note:** External antennas (U.FL pigtail cables), host carrier board, and power supply are not included unless specified in the order. Contact sales@compex.com.sg for accessory options.

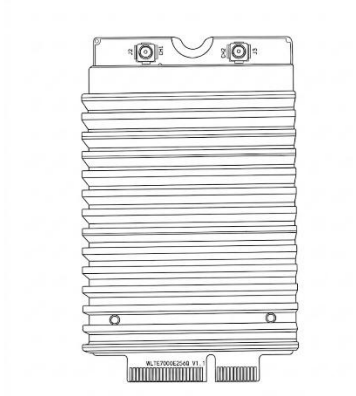
If any item is missing or damaged, contact Compex Technical Support (see Chapter 10) before proceeding.

3. Hardware Overview

The WLTE7002E55 is a radio-only Wi-Fi 7 module designed to be installed into a host platform's M.2 E Key slot. To install on another slot such as an M.2 key slot, an M.2 key to M.2 E Key adapter may be used. All wireless baseband and RF processing is handled onboard the module; the host platform supplies power and exchanges data over the PCIe 3.0 interface.

3.1 Module Layout

The WLTE7002E55 features the following major components and connectors:

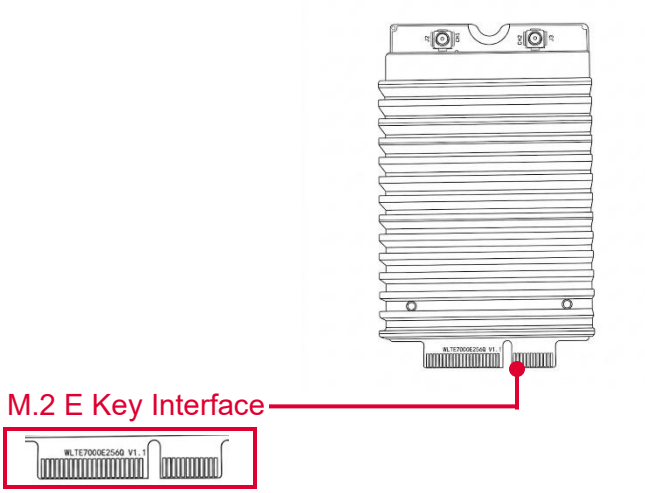


Chipset	Qualcomm QCN6224/6274 'Waikiki' series (Commercial grade) Qualcomm QCN9274-I 'Waikiki' series (Industrial grade)
Reference Design	WK01.4
Host Interface	M.2 E Key Interface with PCIe 3.0
RF Connectors	2× U.FL Connectors (CH0, CH1)
System Memory	2Mbit serial I²C bus EEPROM
Dimensions (W × H × D)	30mm × 52mm × 20.1mm

3.2 Connector Descriptions

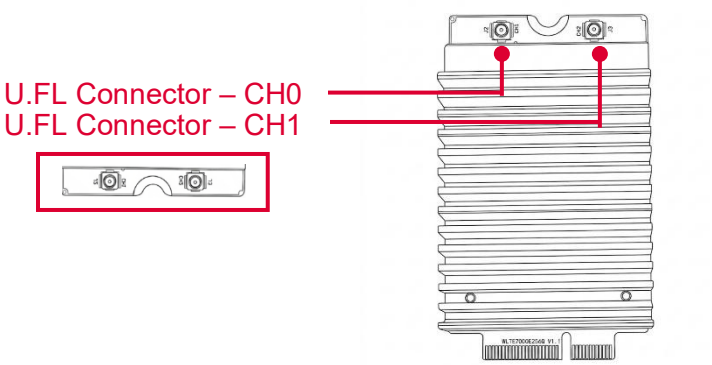
M.2 E Key Edge Connector

- Standard M.2 E Key (PCIe 3.0) edge connector along the bottom edge of the module.
- Carries PCIe data lanes, 3.3V power input, ground, and control signals to the host platform.



U.FL RF Connectors

- 2× U.FL Connectors (CH0 and CH1) located at the top edge of the module.
- CH0 and CH1 jointly support 5GHz (5-L) and 5GHz (5-H) dual-band concurrent operation.
- Connect suitable external antennas rated for the 5GHz (5-L) and 5GHz (5-H) sub-bands.



3.3 Hardware Pinouts

M.2 E Key Slot Pin Assignment

Top side		Bottom side	
1	GND	2	VDD_3V3
3	NC	4	VDD_3V3
5	NC	6	NC
7	GND	8	NC
9	NC	10	NC
11	NC	12	NC
13	NC	14	NC
15	NC	16	NC
17	NC	18	GND
19	NC	20	NC
21	NC	22	NC
23	NC		
Mechanical key M.2 E Key			
33	GND	32	NC
35	PCIE0_TX0_P	34	NC
37	PCIE0_TX0_N	36	NC
39	GND	38	NC
41	PCIE0_RX0_P	40	NC
43	PCIE0_RX0_N	42	NC
45	GND	44	NC
47	REFCLK_P	46	NC
49	REFCLK_N	48	NC
51	GND	50	NC
53	CLKREQ_3V3	52	PERST_3V3
55	WAKE_3V3	54	NC
57	GND	56	W_DISABLE_1V8
59	PCIE0_TX1_P	58	NC
61	PCIE0_TX1_N	60	NC
63	GND	62	NC
65	PCIE0_RX1_P	64	NC
67	PCIE0_RX1_N	66	NC
69	GND	68	NC
71	NC	70	NC
73	NC	72	VDD_3V3
75	GND	74	VDD_3V3

4. Radio Module Specifications

4.1 Wi-Fi Capability

Wi-Fi Standards	5GHz (5-L): 802.11a/n/ac/ax/be 5GHz (5-H): 802.11a/n/ac/ax/be
Bands	5GHz (5-L) + 5GHz (5-H) Dual-Band Concurrent
MIMO Configuration	2×2 MU-MIMO
Max Physical Data Rate	5GHz (5-L): up to 4324 Mbps 5GHz (5-H): up to 4324 Mbps
Frequency Range	5GHz (5-L): 5.180 ~ 5.320GHz 5GHz (5-H): 5.500 ~ 5.825GHz
Modulation Techniques	OFDMA: BPSK, QPSK, DBPSK, DQPSK, 16-QAM, 64-QAM, 256-QAM, 1024-QAM, 4096-QAM
Channel Spectrum Widths	Supports 20/40/80/160/240MHz at 5GHz (5-L) Supports 20/40/80/160/240MHz at 5GHz (5-H)
TX Power	Max 18dBm per chain @ 5GHz (5-L) Max 17dBm per chain @ 5GHz (5-H)
RF Connectors	2× U.FL Connectors (CH0, CH1)

4.2 Notes & Recommendations

- Use external antennas rated for both the 5GHz (5-L) and 5GHz (5-H) sub-bands to fully utilize the dual-band concurrent capability.
- The QCN9274-I industrial-grade variant is recommended for deployments requiring extended temperature operation beyond the standard range. Both variants share the same standard operating range of -20°C to 70°C; operation beyond this range requires a customized heatsink solution (contact sales).
- Refer to the Linux driver/SDK documentation supplied by Compex or Qualcomm for channel and regulatory domain configuration.
- Actual throughput will vary depending on host platform, driver configuration, channel width, and RF environment.

5. Mechanical Specifications

5.1 Module Dimensions

Dimensions (W × H × D)	30mm × 52mm × 20.1mm
Mounting Hole Diameter	Ø3.10mm
Form Factor	Standard M.2 E Key with heatsink

5.2 Environmental Ratings

Operating Temperature	-20°C to 70°C
Storage Temperature	-40°C to 90°C
Operating Humidity	5% to 95%, Non-Condensing
Storage Humidity	Max. 90%

5.3 Mounting & Installation Notes

- Secure with the mounting screw at the designated Ø3.10mm hole if the host chassis provides one.
- Ensure adequate airflow or thermal contact with the heatsink fins for sustained high-throughput operation.
- For industrial-grade ambient temperatures, contact your sales representative for a customized heatsink solution.

6. Power Specifications

6.1 Power Requirements

Operating Voltage	3.3V DC
Power Consumption	8.5W (Max)
Power Source	Supplied via M.2 E Key edge connector from host platform

6.2 Power Delivery Protection

- The host platform's M.2 E Key slot is responsible for providing regulated 3.3V power and short-circuit/overcurrent protection.
- Ensure the host power rail can supply the module's peak 8.5W power consumption without voltage droop.

6.3 Notes & Recommendations

- Use a host platform with a stable, well-regulated 3.3V M.2 E Key power rail.
- Avoid hot-plugging the module; always power down the host before installation or removal.
- For high-duty-cycle or industrial deployments, verify thermal dissipation is adequate at sustained 8.5W operation.

7. Installation & Integration

7.1 Pre-Installation Checklist

- Power off and disconnect the host platform before installation.
- Verify the host platform provides a M.2 E Key slot compatible with PCIe 3.0.
- Prepare external antennas rated for 5GHz (5-L) and 5GHz (5-H) with U.FL connectors or pigtail adapters.

7.2 Module Installation

- Align the WLTE7002E55 module's gold-finger edge connector with the host M.2 E Key slot.
- Insert at a slight angle (typically 15–20°) and press down firmly until fully seated.
- Rotate the module flat and secure with the mounting screw if provided by the host chassis.

7.3 Power Connection

- Power is supplied automatically through the M.2 E Key edge connector; no separate power cable is required.
- Confirm the host platform's M.2 E Key slot delivers a stable 3.3V supply before powering on.

7.4 Antenna Connection

- Connect external antennas to the CH0 and CH1 U.FL connectors.
- Ensure antenna cables are routed without sharp bends to avoid signal loss or connector damage.

8. Troubleshooting

Module Not Detected	•Verify the module is fully seated in the M.2 E Key slot and the retaining screw (if present) is secured. •Confirm the host platform's M.2 E Key slot supports PCIe 3.0 and provides 3.3V power. •Check that the appropriate Linux driver/SDK package is installed on the host.
No Wireless Signal / Weak RF Performance	•Verify external antennas are securely connected to the CH0 and CH1 U.FL connectors. •Confirm antennas are rated for the 5GHz (5-L) and/or 5GHz (5-H) sub-bands in use. •Check for physical damage to U.FL connectors or antenna cables.
Overheating or Unexpected Shutdown	•Ensure adequate airflow or thermal contact with the heatsink fins for sustained high-throughput operation. •Confirm ambient temperature is within the rated -20°C to 70°C operating range. •For sustained high-throughput or industrial use, consider a customized heatsink solution.

9. Safety Precautions

- Always power off and disconnect the host system before installing or removing the module.
- Handle the module by its edges; avoid touching the gold-finger connector or RF components.
- Use proper ESD (electrostatic discharge) precautions, including a grounded wrist strap, when handling the module.
- Do not operate the module without an antenna connected, as this may damage the transmitter.
- Do not attempt to modify or repair the module; contact Compex Technical Support for service.

10. Technical Support

Compex Systems Pte Ltd provides engineering and technical support for the WLTE7002E55. For technical assistance, integration support, or to report a hardware issue, please contact:

Company	Compex Systems Pte Ltd
Headquarters	Singapore
Sales Enquiries	sales@compex.com.sg
Technical Support	https://compex.com.sg/support-downloads/
Website	https://compex.com.sg
Product Page (WLTE7002E55)	https://compex.com.sg/shop/wifi-module/802-11be/wlte7002e55-wifi7-11be-qcn6274-qcn9274/
Qualcomm Design Centre	Qualcomm Authorized Design Centre (ADC) since 2014

Before contacting support, please:

- Note the firmware version (visible via webUI: System > Software, or via SSH/serial console: cat /etc/openwrt_release)
- Record the MAC address of the board (visible on PCB label).
- Describe the issue with steps to reproduce, observed symptoms, and host platform details.

For sample requests, pre-production evaluations, or OEM/ODM partnership enquiries, contact the Compex sales team at sales@compex.com.sg.

11. Full Specifications

Model	WLTE7002E55
Chipset	Qualcomm QCN6224/6274 'Waikiki' series for Commercial grade Qualcomm QCN9274-I 'Waikiki' series for Industrial grade
System Memory	2Mbit serial I²C bus EEPROM
Reference Design	WK01.4
Host Interface	M.2 E Key Interface with PCIe 3.0
Operating Voltage	3.3V
Power Consumption	8.5W (Max)
Wireless	2×2 5GHz (5-L) 802.11a/n/ac/ax/be, max 18dBm per chain 2×2 5GHz (5-H) 802.11a/n/ac/ax/be, max 17dBm per chain 2× U.FL Connectors
Frequency Range	5GHz (5-L): 5.180 ~ 5.320GHz 5GHz (5-H): 5.500 ~ 5.825GHz
Modulation Techniques	OFDMA: BPSK, QPSK, DBPSK, DQPSK, 16-QAM, 64-QAM, 256-QAM, 1024-QAM, 4096-QAM
Channel Spectrum Widths	Supports 20/40/80/160/240MHz at 5GHz (5-L) Supports 20/40/80/160/240MHz at 5GHz (5-H)
Operating System	Linux
Certification	FCC, CE, IC Certified, REACH & RoHS Compliance
Environmental Temperature	Operating: -20°C to 70°C Storage: -40°C to 90°C
Environmental Humidity	Operating: 5% to 95%, Non-Condensing Storage: Max. 90%
Dimensions (W × H × D)	30mm × 52mm × 20.1mm

Notes

- For industrial-grade environmental temperature requirements, contact your sales representative for a customized heatsink solution.

12. Regulatory Information

Declaration of Conformity

The WLTE7002E55 is FCC, CE, and IC Certified and designed to comply with applicable regional regulatory requirements. The WLTE7002E55 is a component-level radio module intended for integration into end products. End-product manufacturers are responsible for obtaining all necessary regulatory certifications (e.g., FCC, CE, IC) for their final product in each target market, including any additional certifications required for the complete host platform assembly.

REACH & RoHS Compliance

This product is manufactured in compliance with REACH Regulation (EC) No 1907/2006 and RoHS Directive 2011/65/EU (amended by 2015/863/EU), restricting the use of hazardous substances in electrical and electronic equipment.

Disposal & Recycling

This product is subject to the Waste Electrical and Electronic Equipment (WEEE) Directive. At the end of its service life, return the product to an authorised recycling facility or contact Compex Systems for take-back options.

Legal Notices
Qualcomm, QCN6224, QCN6274, and QCN9274 are trademarks or registered trademarks of Qualcomm Technologies, Inc. Compex® and the Compex logo are trademarks of Compex Systems Pte Ltd. All other trademarks are the property of their respective owners.

Copyright
© 2026 Compex Systems Pte Ltd. All rights reserved.